

**Listing of the Claims:**

This listing of claims will replace, without prejudice, all prior versions, and listings, of claims in the application:

Claims 1-8 (cancelled).

9. (Previously Presented) A method for attaching at least one chip in a housing, the housing being optically transparent to radiation of at least one predefined transmission wavelength, the method comprising:

applying an adhesive layer between the at least one chip and the housing; and  
irradiating the adhesive layer through the housing using radiation of the transmission wavelength for curing.

10. (Previously Presented) The method as recited in claim 9, wherein the housing is a premold housing or a plastic housing which is transparent to radiation in at least one of a visible range and an ultraviolet range.

11. (Previously Presented) The method as recited in claim 10, wherein the radiation is light in the visible range or in the ultraviolet range.

12. (Previously Presented) The method as recited in claim 9, wherein the radiation comes from a side facing away from the chip and hits the adhesive layer.

13. (Previously Presented) The method as recited in claim 9, wherein the adhesive layer is made of an adhesive which cures under ultraviolet or visible light.

14. (Previously Presented) A system, comprising:

at least one chip in a housing, the housing being optically transparent to radiation of at least one predefined transmission wavelength; and  
an adhesive layer between the at least one chip and the housing, the adhesive layer being cured via irradiation through the housing using radiation of the transmission wavelength.

15. (Previously Presented) The system as recited in claim 14, wherein the at least one chip is a micromechanical chip.

16. (Previously Presented) A device for attaching at least one chip in a housing, the housing being optically transparent to radiation of at least one predefined transmission wavelength, comprising:

a radiation source which is positioned in relation to the housing so that an adhesive layer located between the at least one chip and the housing is irradiated through the housing by radiation of the transmission wavelength from the radiation source for curing.